

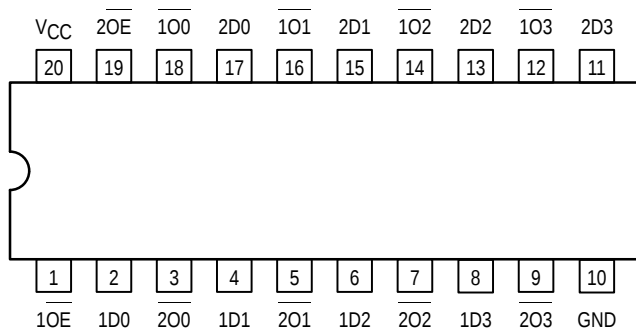
Low-Voltage CMOS Octal Buffer With 5V-Tolerant Inputs and Outputs (3-State, Inverting)

The MC74LCX240 is a high performance, inverting octal buffer operating from a 2.7 to 3.6V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance. A V_I specification of 5.5V allows MC74LCX240 inputs to be safely driven from 5V devices. The MC74LCX240 is suitable for memory address driving and all TTL level bus oriented transceiver applications.

Current drive capability is 24mA at the outputs. The Output Enable (OE) input, when HIGH, disables the outputs by placing them in a HIGH Z condition.

- Designed for 2.7 to 3.6V V_{CC} Operation
- 5V Tolerant — Interface Capability With 5V TTL Logic
- Supports Live Insertion and Withdrawal
- I_{OFF} Specification Guarantees High Impedance When $V_{CC} = 0V$
- LVTTTL Compatible
- LVC MOS Compatible
- 24mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current in All Three Logic States (10 μ A)
Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 500mA
- ESD Performance: Human Body Model >2000V; Machine Model >200V

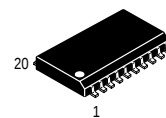
Pinout: 20-Lead (Top View)



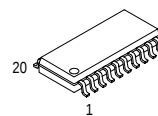
MC74LCX240

LCX

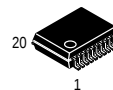
**LOW-VOLTAGE CMOS
OCTAL BUFFER**



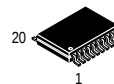
DW SUFFIX
PLASTIC SOIC
CASE 751D-04



M SUFFIX
PLASTIC SOIC EIAJ
CASE 967-01



SD SUFFIX
PLASTIC SSOP
CASE 940C-03



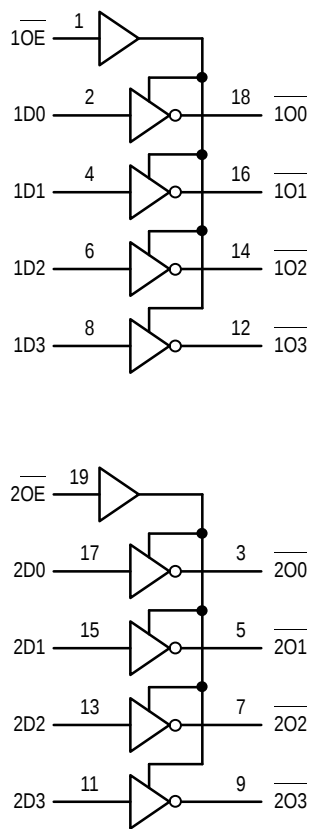
DT SUFFIX
PLASTIC TSSOP
CASE 948E-02

PIN NAMES

Pins	Function
nOE	Output Enable Inputs
1Dn, 2Dn	Data Inputs
1On, 2On	3-State Outputs



LOGIC DIAGRAM



INPUTS		OUTPUTS
10E 20E	1Dn 2Dn	10n, 20n
L	L	H
L	H	L
H	X	Z

H = High Voltage Level; L = Low Voltage Level; Z = High Impedance State; X = High or Low Voltage Level and Transitions Are Acceptable, for I_{CC} reasons, DO NOT FLOAT Inputs

ABSOLUTE MAXIMUM RATINGS*

Symbol	Parameter	Value	Condition	Unit
V_{CC}	DC Supply Voltage	-0.5 to $+7.0$		V
V_I	DC Input Voltage	$-0.5 \leq V_I \leq +7.0$		V
V_O	DC Output Voltage	$-0.5 \leq V_O \leq +7.0$	Output in 3-State	V
		$-0.5 \leq V_O \leq V_{CC} + 0.5^1$	Output in HIGH or LOW State	V
I_{IK}	DC Input Diode Current	-50	$V_I < \text{GND}$	mA
I_{OK}	DC Output Diode Current	-50	$V_O < \text{GND}$	mA
		$+50$	$V_O > V_{CC}$	mA
I_O	DC Output Source/Sink Current	± 50		mA
I_{CC}	DC Supply Current Per Supply Pin	± 100		mA
I_{GND}	DC Ground Current Per Ground Pin	± 100		mA
T_{STG}	Storage Temperature Range	-65 to $+150$		$^{\circ}\text{C}$

* Absolute maximum continuous ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute-maximum-rated conditions is not implied.

1. I_O absolute maximum rating must be observed.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Typ	Max	Unit
V_{CC}	Supply Voltage	2.0	3.3	3.6	V
	Operating Data Retention Only	1.5	3.3	3.6	V
V_I	Input Voltage	0		5.5	V
V_O	Output Voltage (HIGH or LOW State) (3-State)	0		V_{CC}	V
		0		5.5	V
I_{OH}	HIGH Level Output Current, $V_{CC} = 3.0\text{V} - 3.6\text{V}$			-24	mA
I_{OL}	LOW Level Output Current, $V_{CC} = 3.0\text{V} - 3.6\text{V}$			24	mA
I_{OH}	HIGH Level Output Current, $V_{CC} = 2.7\text{V} - 3.0\text{V}$			-12	mA
I_{OL}	LOW Level Output Current, $V_{CC} = 2.7\text{V} - 3.0\text{V}$			12	mA
T_A	Operating Free-Air Temperature	-40		$+85$	$^{\circ}\text{C}$
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate, V_{IN} from 0.8V to 2.0V, $V_{CC} = 3.0\text{V}$	0		10	ns/V

DC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic	Condition	$T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$		Unit
			Min	Max	
V_{IH}	HIGH Level Input Voltage (Note 1)	$2.7\text{V} \leq V_{CC} \leq 3.6\text{V}$	2.0		V
V_{IL}	LOW Level Input Voltage (Note 1)	$2.7\text{V} \leq V_{CC} \leq 3.6\text{V}$		0.8	V
V_{OH}	HIGH Level Output Voltage	$2.7\text{V} \leq V_{CC} \leq 3.6\text{V}$; $I_{OH} = -100\mu\text{A}$	$V_{CC} - 0.2$		V
		$V_{CC} = 2.7\text{V}$; $I_{OH} = -12\text{mA}$	2.2		
		$V_{CC} = 3.0\text{V}$; $I_{OH} = -18\text{mA}$	2.4		
		$V_{CC} = 3.0\text{V}$; $I_{OH} = -24\text{mA}$	2.2		
V_{OL}	LOW Level Output Voltage	$2.7\text{V} \leq V_{CC} \leq 3.6\text{V}$; $I_{OL} = 100\mu\text{A}$		0.2	V
		$V_{CC} = 2.7\text{V}$; $I_{OL} = 12\text{mA}$		0.4	
		$V_{CC} = 3.0\text{V}$; $I_{OL} = 16\text{mA}$		0.4	
		$V_{CC} = 3.0\text{V}$; $I_{OL} = 24\text{mA}$		0.55	

1. These values of V_I are used to test DC electrical characteristics only. Functional test should use $V_{IH} \geq 2.4\text{V}$, $V_{IL} \leq 0.5\text{V}$.

DC ELECTRICAL CHARACTERISTICS (continued)

Symbol	Characteristic	Condition	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$		Unit
			Min	Max	
I_I	Input Leakage Current	$2.7\text{V} \leq V_{CC} \leq 3.6\text{V}; 0\text{V} \leq V_I \leq 5.5\text{V}$		± 5.0	μA
I_{OZ}	3-State Output Current	$2.7 \leq V_{CC} \leq 3.6\text{V}; 0\text{V} \leq V_O \leq 5.5\text{V}; V_I = V_{IH} \text{ or } V_{IL}$		± 5.0	μA
I_{OFF}	Power-Off Leakage Current	$V_{CC} = 0\text{V}; V_I \text{ or } V_O = 5.5\text{V}$		10	μA
I_{CC}	Quiescent Supply Current	$2.7 \leq V_{CC} \leq 3.6\text{V}; V_I = \text{GND or } V_{CC}$		10	μA
		$2.7 \leq V_{CC} \leq 3.6\text{V}; 3.6 \leq V_I \text{ or } V_O \leq 5.5\text{V}$		± 10	μA
ΔI_{CC}	Increase in I_{CC} per Input	$2.7 \leq V_{CC} \leq 3.6\text{V}; V_{IH} = V_{CC} - 0.6\text{V}$		500	μA

AC CHARACTERISTICS ($t_R = t_F = 2.5\text{ns}; C_L = 50\text{pF}; R_L = 500\Omega$)

Symbol	Parameter	Waveform	Limits			Unit
			T _A = −40°C to +85°C			
			V _{CC} = 3.0V to 3.6V		V _{CC} = 2.7V	
			Min	Max	Max	
t _{PLH} t _{PHL}	Propagation Delay Input to Output	1	1.5 1.5	6.5 6.5	7.5 7.5	ns
t _{PZH} t _{PZL}	Output Enable Time to High and Low Level	2	1.5 1.5	8.0 8.0	9.0 9.0	ns
t _{PHZ} t _{PLZ}	Output Disable Time From High and Low Level	2	1.5 1.5	7.0 7.0	8.0 8.0	ns
t _{OSHL} t _{OSLH}	Output-to-Output Skew (Note 1)			1.0 1.0		ns

1. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}); parameter guaranteed by design.

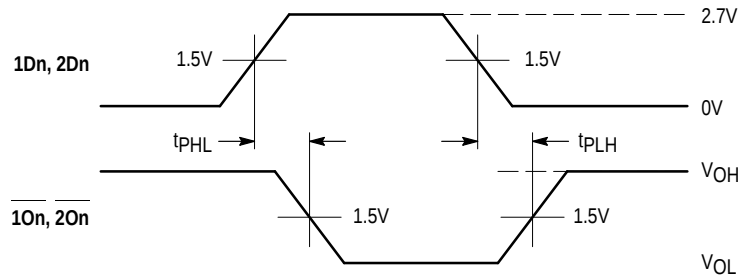
DYNAMIC SWITCHING CHARACTERISTICS

Symbol	Characteristic	Condition	$T_A = +25^{\circ}\text{C}$			Unit
			Min	Typ	Max	
V_{OLP}	Dynamic LOW Peak Voltage ¹	$V_{CC} = 3.3\text{V}, C_L = 50\text{pF}, V_{IH} = 3.3\text{V}, V_{IL} = 0\text{V}$		0.8		V
V_{OLV}	Dynamic LOW Valley Voltage ¹	$V_{CC} = 3.3\text{V}, C_L = 50\text{pF}, V_{IH} = 3.3\text{V}, V_{IL} = 0\text{V}$		0.8		V

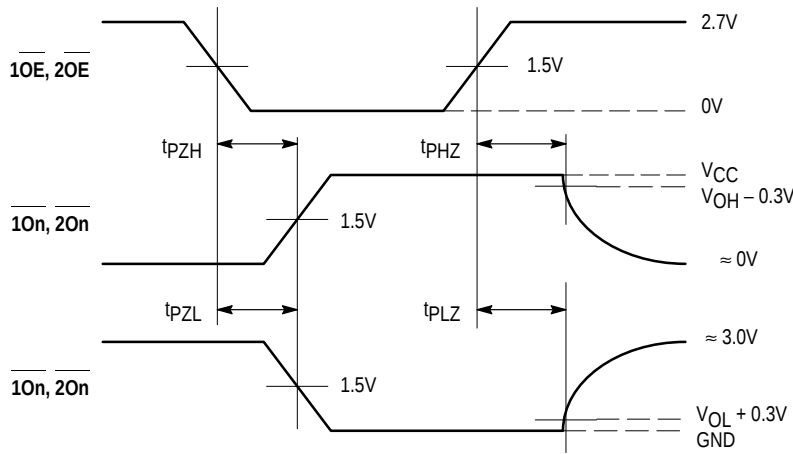
1. Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C_{PD}	Power Dissipation Capacitance	10MHz, $V_{CC} = 3.3\text{V}, V_I = 0\text{V or } V_{CC}$	25	pF
C_{IN}	Input Capacitance	$V_{CC} = 3.3\text{V}, V_I = 0\text{V or } V_{CC}$	7	pF
C_{OUT}	Output Capacitance	$V_{CC} = 3.3\text{V}, V_I = 0\text{V or } V_{CC}$	8	pF

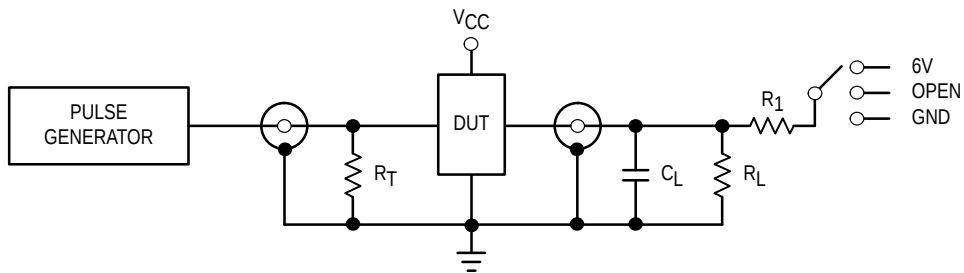


WAVEFORM 1 – PROPAGATION DELAYS
 $t_R = t_F = 2.5\text{ns}$, 10% to 90%; $f = 1\text{MHz}$; $t_W = 500\text{ns}$



WAVEFORM 2 – OUTPUT ENABLE AND DISABLE TIMES
 $t_R = t_F = 2.5\text{ns}$, 10% to 90%; $f = 1\text{MHz}$; $t_W = 500\text{ns}$

Figure 1. AC Waveforms



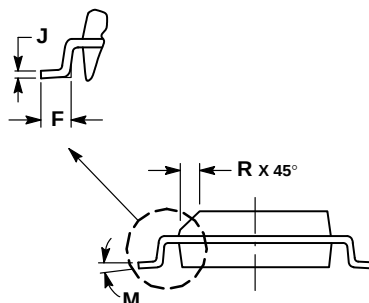
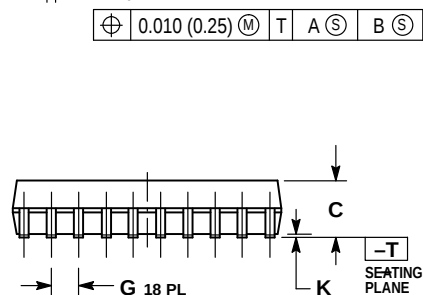
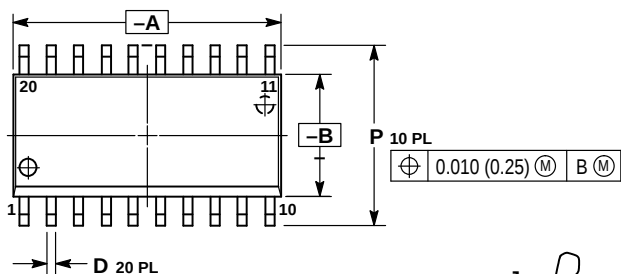
TEST	SWITCH
t_{PLH} , t_{PHL}	Open
t_{PZL} , t_{PLZ}	6V
Open Collector/Drain t_{PLH} and t_{PHL}	6V
t_{PZH} , t_{PHZ}	GND

$C_L = 50\text{pF}$ or equivalent (Includes jig and probe capacitance)
 $R_L = R_1 = 500\Omega$ or equivalent
 $R_T = Z_{OUT}$ of pulse generator (typically 50Ω)

Figure 2. Test Circuit

OUTLINE DIMENSIONS

DW SUFFIX
PLASTIC SOIC PACKAGE
CASE 751D-04
ISSUE E

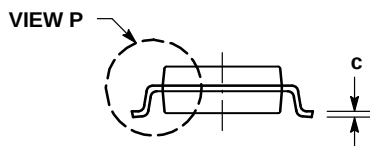
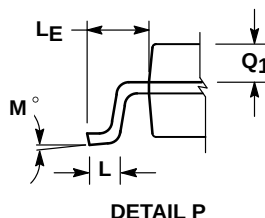
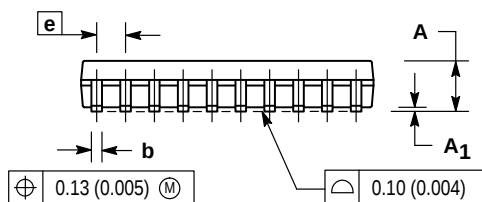
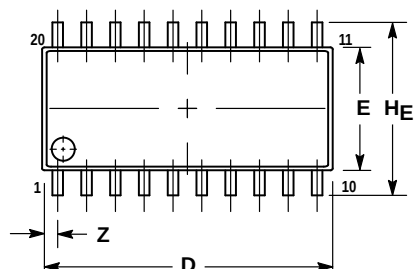


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.150 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	12.65	12.95	0.499	0.510
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.50	0.90	0.020	0.035
G	1.27 BSC		0.050 BSC	
J	0.25	0.32	0.010	0.012
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

M SUFFIX
PLASTIC SOIC EIAJ PACKAGE
CASE 967-01
ISSUE O



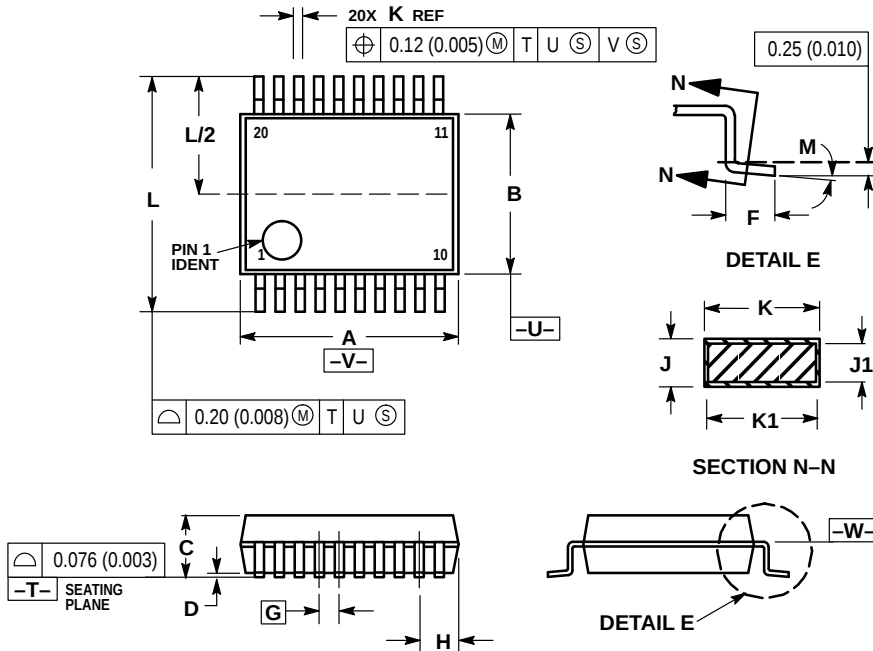
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A1	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	12.35	12.80	0.486	0.504
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0°	10°	0°	10°
Q1	0.70	0.90	0.028	0.035
Z	---	0.81	---	0.032

OUTLINE DIMENSIONS

SD SUFFIX
PLASTIC SSOP PACKAGE
CASE 940C-03
ISSUE B

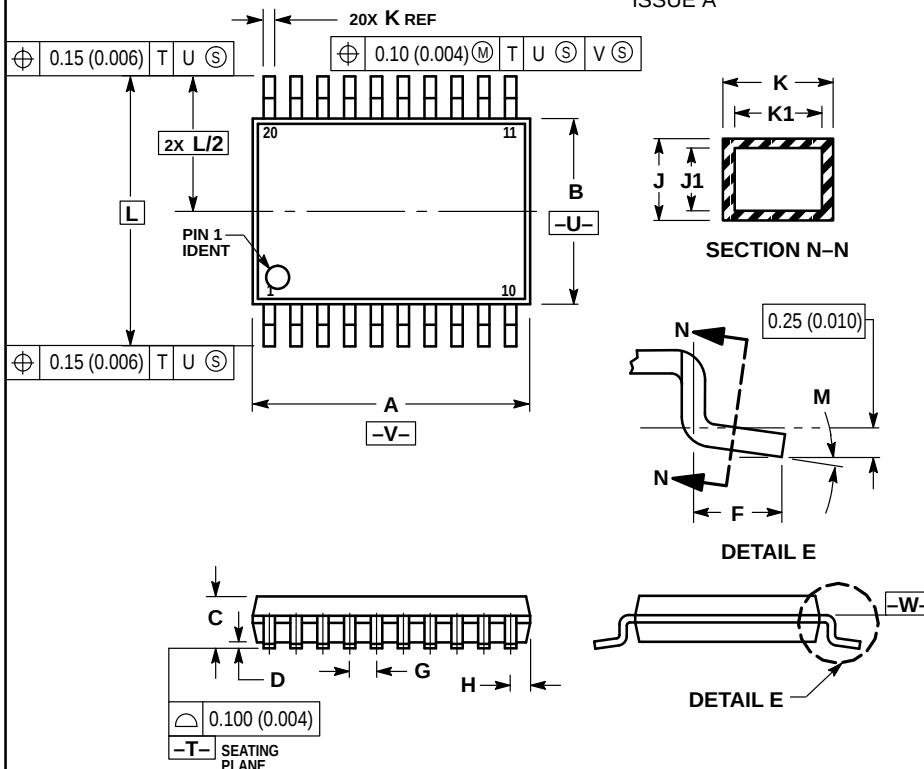


NOTES:

- 13 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 14 CONTROLLING DIMENSION: MILLIMETER.
- 15 DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- 16 DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- 17 DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION/INTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF K DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR INTRUSION SHALL NOT REDUCE DIMENSION K BY MORE THAN 0.07 (0.002) AT LEAST MATERIAL CONDITION.
- 18 TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- 19 DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	7.07	7.33	0.278	0.288
B	5.20	5.38	0.205	0.212
C	1.73	1.99	0.068	0.078
D	0.05	0.21	0.002	0.008
F	0.63	0.95	0.024	0.037
G	0.65 BSC		0.026 BSC	
H	0.59	0.75	0.023	0.030
J	0.09	0.20	0.003	0.008
J1	0.09	0.16	0.003	0.006
K	0.25	0.38	0.010	0.015
K1	0.25	0.33	0.010	0.013
L	7.65	7.90	0.301	0.311
M	0°	8°	0°	8°

DT SUFFIX
PLASTIC TSSOP PACKAGE
CASE 948E-02
ISSUE A



NOTES:

- 6 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 7 CONTROLLING DIMENSION: MILLIMETER.
- 8 DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- 9 DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
- 10 DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
- 11 TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- 12 DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	6.40	6.60	0.252	0.260
B	4.30	4.50	0.169	0.177
C	—	1.20	—	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

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MC74LCX240/D

